SUBSTRATE POLISHER AND POLISHING METHOD

ABSTRACT

A polisher for locally polishing a substrate is provided. The polisher includes a polishing member having a processing surface that comes into contact with the substrate and is smaller than the substrate, a pressing mechanism for pressing the polishing member against the substrate, a first drive mechanism for imparting motion to the polishing member in a first motion direction parallel to a surface of the substrate, a second drive mechanism for imparting motion to the polishing member in a second motion direction perpendicular to the first motion direction and having a component parallel to the surface of the substrate, and a controller for controlling the action of the polisher.

Representative drawing: Fig. 1